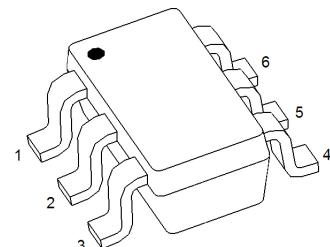


40V P-Channel MOSFETs

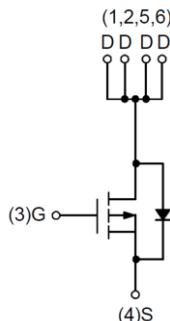
V_{(BR)DSS}	R_{DS(on)MAX}	I_D
-40V	35mΩ@-10V	-7A
	50mΩ@-4.5V	

SOT23-6L

FEATURE

- High Cell Density Trenched P-ch MOSFETs
- Excellent R_{DSON}
- Low Gate Charge

APPLICATION

- Power Switching Application
- Hard Switched and High Frequency Circuits
- DC-DC Converter

Equivalent Circuit

ABSOLUTE MAXIMUM RATINGS (T_C=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	-40	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current ¹	I _D	-7	A
Pulsed Drain Current ²	I _{DM}	-28	A
Single Pulse Avalanche Energy ³	E _{AS}	40	mJ
Avalanche Current	I _{AS}	-27	A
Power Dissipation ⁴	P _D	1.1	W
Thermal Resistance from Junction to Ambient ¹	R _{θJA}	110	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~+150	°C

MOSFET ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-40			V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = -32\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	nA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.2	-1.5	-2.5	V
Drain-source on-resistance ²	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -5\text{A}$		28	35	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -4\text{A}$		38	50	
Forward transconductance	g_{FS}	$V_{\text{DS}} = -5\text{V}, I_D = -8\text{A}$		12		S
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		1415		pF
Output capacitance	C_{oss}			134		
Reverse transfer capacitance	C_{rss}			102		
Switching Characteristics						
Total gate charge@-4.5V	Q_g	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = -4.5\text{V}, I_D = -1\text{A}$		11.5		nC
Gate-source charge	Q_{gs}			3.5		
Gate-drain charge	Q_{gd}			3.3		
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -15\text{V}, V_{\text{GS}} = -10\text{V}, R_G = 3.3\Omega, I_D = -1\text{A}$		22		ns
Turn-on rise time	t_r			15.7		
Turn-off delay time	$t_{\text{d}(\text{off})}$			59		
Turn-off fall time	t_f			5.5		
Diode Characteristics						
Continuous Source Current ^{1,5}	I_s	$V_G = V_D = 0\text{V}$, Force Current			-7	A
Diode Forward Voltage ²	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_s = -1\text{A}, T_J = 25^\circ\text{C}$			-1.2	V

Notes:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The E_{AS} data shows Max. rating . The test condition is $V_{\text{DD}} = -25\text{V}, V_{\text{GS}} = -10\text{V}, L = 0.1\text{mH}, I_{\text{AS}} = -27\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

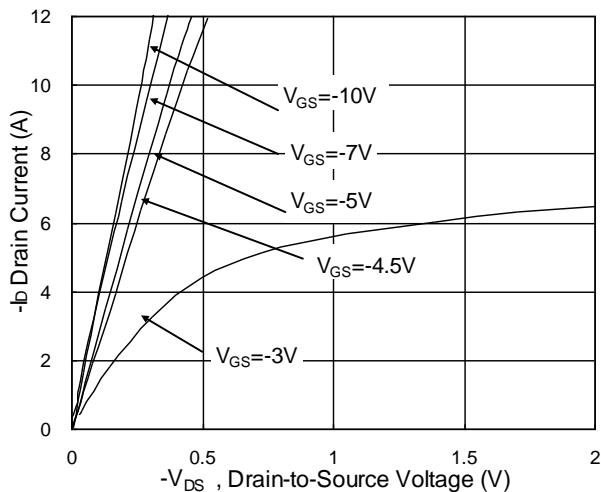


Fig.1 Typical Output Characteristics

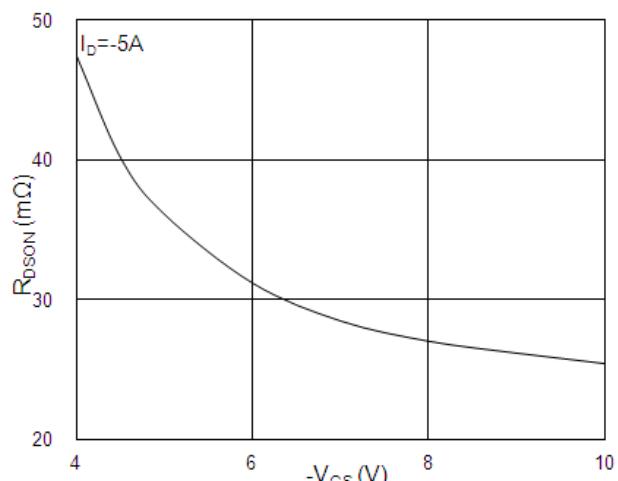


Fig.2 On-Resistance vs. Gate-Source Voltage

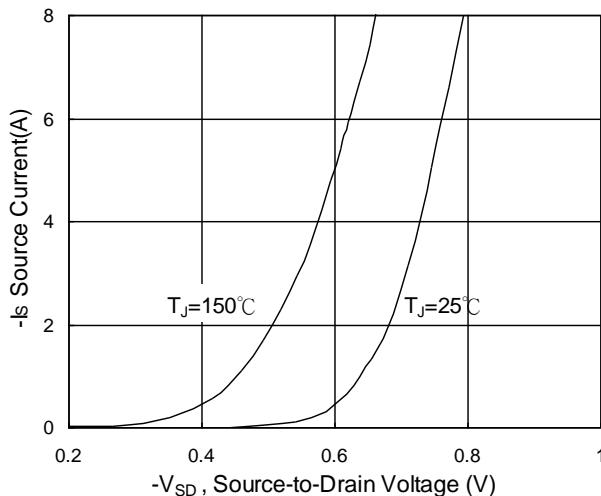


Fig.3 Forward Characteristics of Reverse

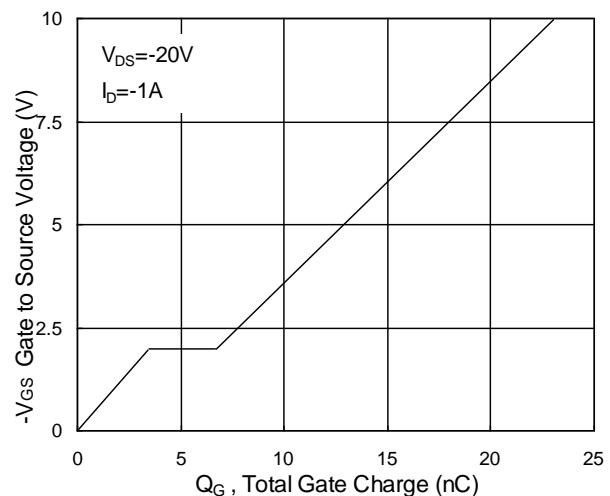


Fig.4 Gate Charge Characteristics

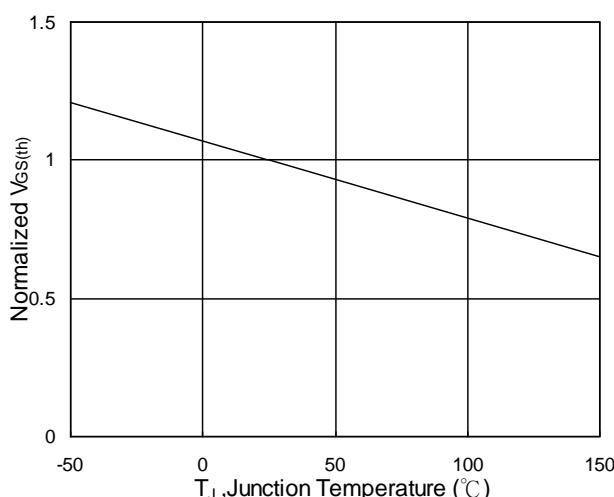


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

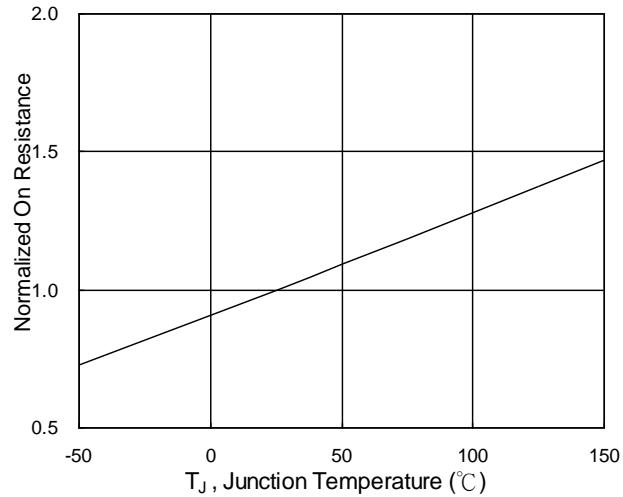
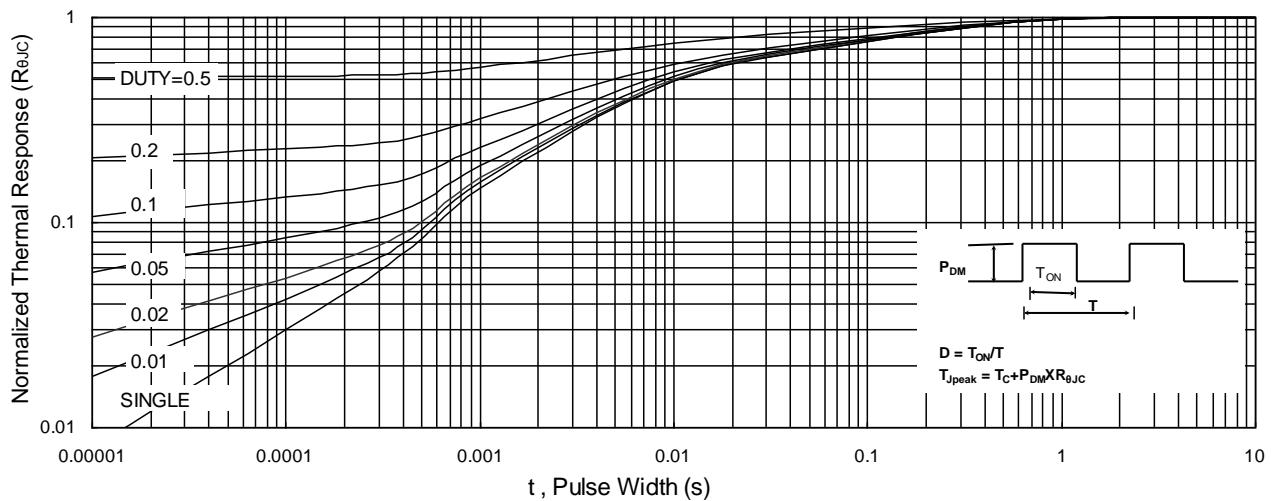
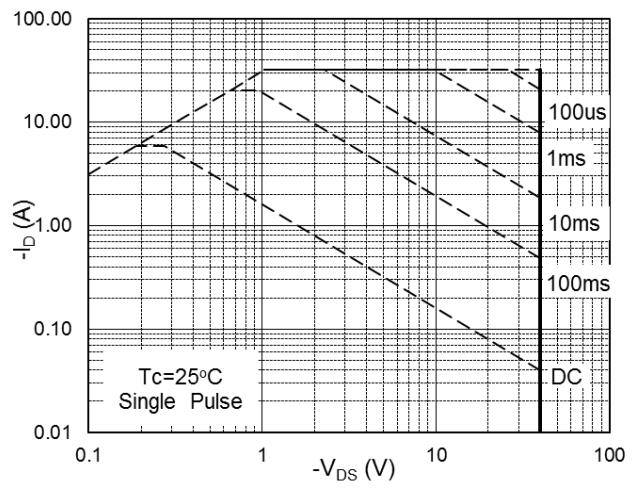
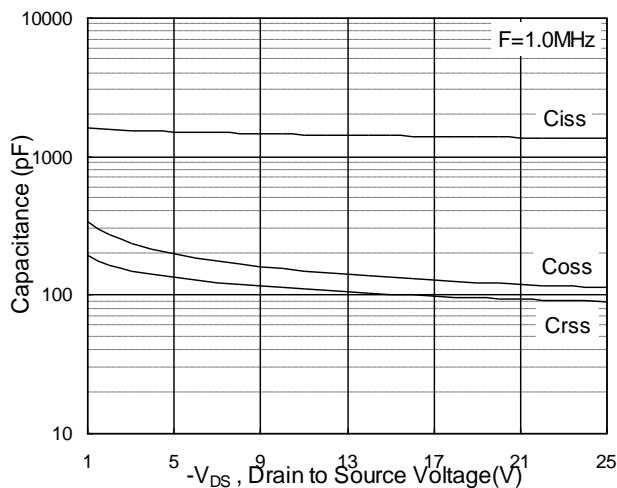
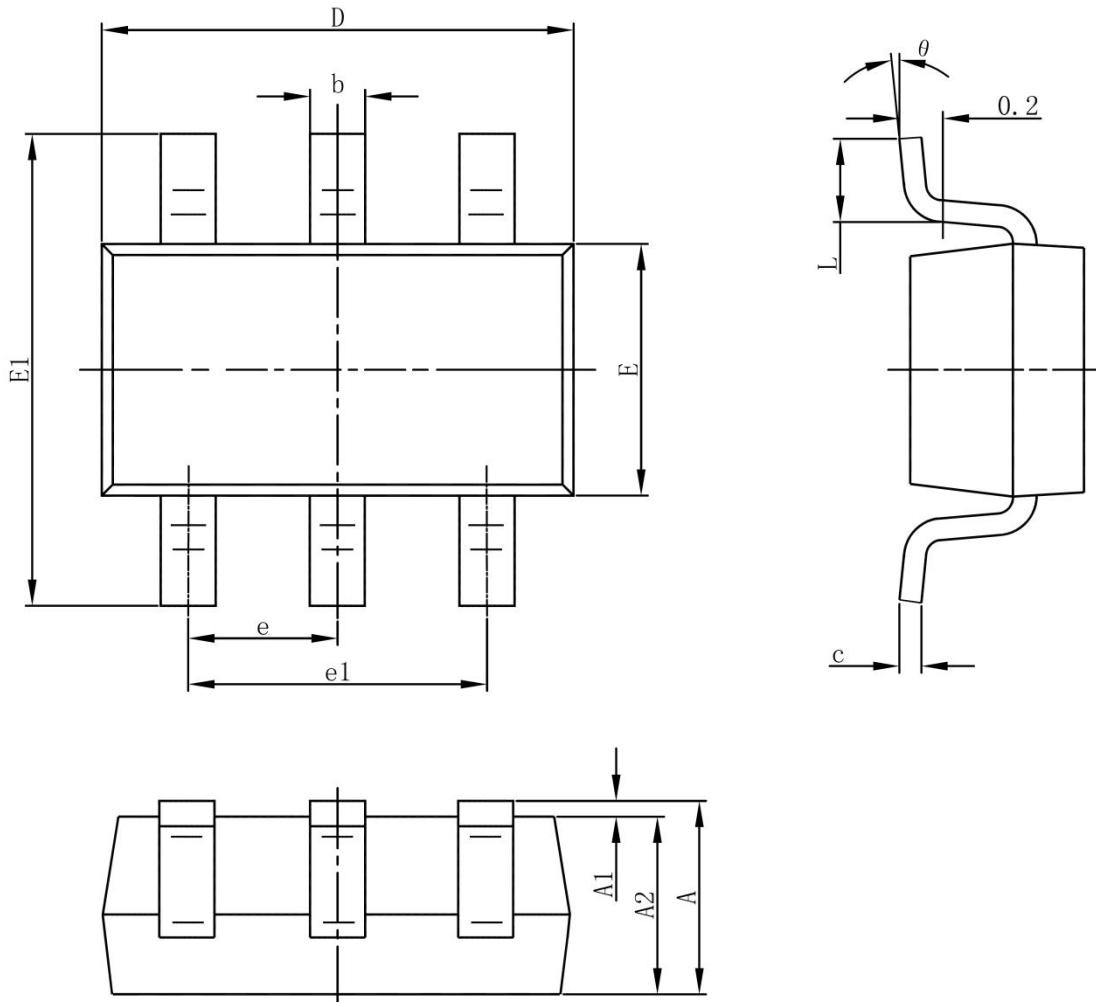


Fig.6 Normalized R_{DSON} vs. T_J

Typical Characteristics



SOT23-6L Package Outline Dimensions


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

V1.0